

The characteristics of lead-coated PCB processed with flux

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Flux is used to improve the soldering characteristics through decreasing the surface tension and removing the oxide film of metal surface of PCB and via hole for electrical connections between layers of PCB. In this study, we examined the characteristics of lead-coated PCB surface and via hole after coating CTP-700, the flux solution to 8 kinds of PCBs with sizes from the minimum of 150x120mm to the maximum of 504x400mm. The lead coating process was made through dipping each PCB which was dipped in the flux solution for 3 seconds into the solder pot of 200°C containing liquid lead. The surface of each PCB was observed through an optical microscope, and the via hole was also observed after cutting and polishing the cross-section. The PCB surface was well coated with lead, and lead was evenly filled on the inside of the via hole.